

SILICONE AND POLYURETHANE RESINS*

REF	Component	mixing ratio	CURING SCHEDULE Recommended	POT LIFE After mixing	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
									BEFORE TG	AFTER TG		

POLYURETHANE RESINS FOR GLOB TOP*

PU201B	2	100/15,4	24 at 48 h at 25°C	1 h at 25°C	30 Pa.S	-40°C					4,7.10 ¹² Ω.cm	Encapsulation - Translucid - UL94VO reconized
PU201N	2	100/4	24 at 48 h at 25°C	1 h 30 at 25°C	70 Pa.S	-40°C					2,6.10 ¹¹ Ω.cm	Encapsulation - Black - UL94VO reconized - High thermal conductivity

SILICONE RESINS FOR STRUCTURAL BONDING*

S303N	2	100/3,4	2 h at 85°C	4 h at 25°C	8 Pa.S	-64°C			2.10 ⁻⁴ /°C		2,5.10 ¹⁵ Ω.cm	Encapsulation - Black - Good thermal conductivity
S323N	2	1/1	2 h at 85°C	24 h at 25°C	8 Pa.S	-64°C	> 500°C	68%	200.10 ⁻⁶ /°C		2,5.10 ¹⁵ Ω.cm	Encapsulation - Black - Good thermal conductivity

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

* for more precision on the technical properties, to refer to the individual data sheet.

Maj 24/01/2007